



Material Composition Sheet

Product: GS9092-CNE3
 Package Type: QFN-56 pin
 Manufacturer: Gennum Corporation

Date: 06-Dec-2006

Component	BOM	Weight of Component (mg)	Substance	Weight of Substance (mg)	Homogeneous Material	
					%	ppm
Die		6.21	Al	0.04	0.64	6441
			Si	6.17	99.35	993559
			Sub-total:	6.21	99.99	1000000
Die Attach	CRM 1076DS	1.09	Ag	0.84	77.06	770642
			Epoxy Resin	0.13	11.92	119266
			Phenol Resin	0.04	3.66	36697
			t-Butylphenylglycidil ether	0.08	7.33	73394
			Sub-total:	1.09	99.97	999999
Internal Lead Finish		1.57	Ag	1.57	100.00	1000000
Leadframe	Olin 7025	99.20	Sub-total:	1.57	100.00	1000000
			Cu	95.43	96.19	961996
			Mg	0.15	0.15	1512
			Ni	2.98	3.00	30040
			Si	0.64	0.64	6452
Mold Compound	EME G770HC	75.09	Sub-total:	99.20	99.98	1000000
			Carbon Black	1.50	1.99	19976
			Epoxy Resin	3.00	3.99	39952
			Phenol Resin	3.00	3.99	39952
			SiO2	67.59	90.01	900120
Terminals Finish		4.60	Sub-total:	75.09	99.98	1000000
			Sn	4.60	100.00	1000000
Wires	AW88	1.67	Sub-total:	4.60	100.00	1000000
			Au	1.67	100.00	1000000
Total:		189.43				

GENNUM CORPORATION

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